



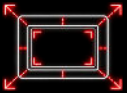
DIRECT IMAGING SYSTEM

MIVA 2200L DI

FLEXIBLE ALLROUNDER
DIRECT IMAGER FOR
PCB IMAGING



HIGH PRODUCTIVITY
Up to 3 photoheads.



LARGE FORMAT IMAGING
Up to 24" × 30".



HIGH RESOLUTION
Structures down to 2 μm available.



FLEXIBLE AUTOMATION
Reel-to-reel and automation ready.



**MIVA
meets
your needs.**

MIVA direct imaging systems combine precision, reliability and innovation to meet the most demanding requirements in microfabrication.

MIVA 2200L DI

NEXT GENERATION DIRECT IMAGING SERIES



TECHNICAL DATA

Machine positional accuracy @21°C	Positioning resolution 0.1 nm
Physical size	H: 77"/195cm, W: 52"/132cm, D: 67"/170cm
Power requirements	400–480 VAC, 50/60 Hz, 5.5 kW (900 W when idle)
Compressed air	Integrated gas filtering system for 120 L/min @ 6 bar (air compressor optional)
Technology	DMD Raster Image Projection Technology / Solid state UV light sources
Environment	Dependent on resist/emulsion sensitivity, yellow/red safe light conditions recommended for loading panels or other media
Recom. temp./humidity	21°C, 50% RH
Media	Resist coated panels, UV films, solder mask, orthochromatic phototooling films or masks up to 20 mm thick
User dialogue	Intuitive surface for operation by keyboard or remote control.
Communications	Local area network, removable media
Protocol emulations	Gerber RS 274-X, PostScript, TIFF (+ on request)
User interface	xDI Multihead control program (Windows compat)
Max. image size	24" × 30" (610 × 762 mm)
Media sizes from	2" × 2" (50 × 50 mm)
Panel registration	Inbuilt coaxial registration camera

PERFORMANCE

Application	15 µm	30 µm
	1LE / 2LE / 3LE	1LE / 2LE / 3LE
Inner Layer	22 / 34 / 46	34 / 50 / 63
Outer Layer	20 / 31 / 42	23 / 39 / 50
Soldermask	9 / 15 / 21	10 / 17 / 23

Note 1: All values in panels/hour.

Note 2: All values include imaging both sides and assume a total load/unload time of 8 sec, based on a panel size of 18" × 24" (457 × 610 mm).

Note 3: All values assume high speed resist types; other resists available upon request.



DART YIELD IMPROVEMENT

Advanced registration and scaling for improved process accuracy + yield.



UP TO 3 PHOTOHEADS

Scalable configuration with up to three photoheads for increased productivity.



HIGH RESOLUTION OPTION

Optional high-resolution structures with 6, 4, 2.5 down to 2 µm.



FLEXIBLE MEDIA HANDLING

Clamping system and reel-to-reel compatibility available.



meets your needs

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MIVA REPRESENTATIVE

